



# **Product Change Notification**

## **114050 - 00**

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**Americas Contact:** [asmo.pcn@intel.com](mailto:asmo.pcn@intel.com)

**Asia Pacific/PRC Contact:** [apacgccb@intel.com](mailto:apacgccb@intel.com)

**Europe Email:** [eccb@intel.com](mailto:eccb@intel.com)

**Japan Email:** [jcb.ijkk@intel.com](mailto:jcb.ijkk@intel.com)

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# Product Change Notification

**Change Notification #:** 114050 - 00  
**Change Title:** **Boxed Intel® NUC Kit NUC5CPYH, Single Pack, Boxed**  
**Intel® NUC Kit NUC5PPYH, Single Pack, PCN 114050-00, Product Design, Product Material**  
**EMI Enhancement, component changes, and guide update.**

**Date of Publication:** August 31, 2015

**Key Characteristics of the Change:**  
Product Design, Product Material

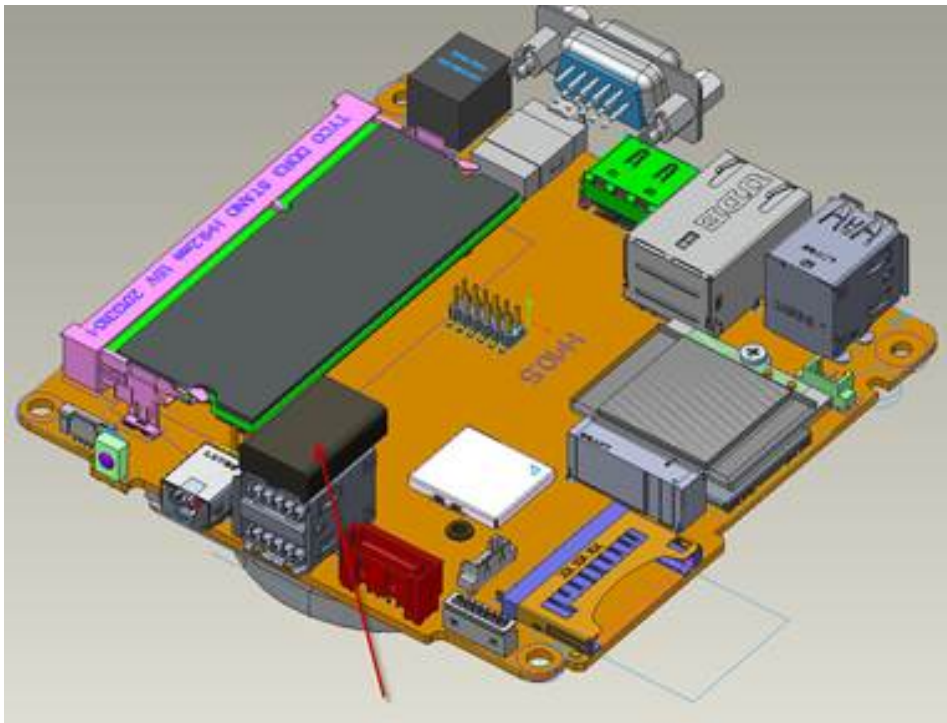
**Forecasted Key Milestones:**

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	Sep 14, 2015
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**Description of Change to the Customer:**

The Intel® NUC Kits NUC5CPYH and NUC5PPYH will have the following changes.

1. There will be an enhancement on the SD Card interface and a gasket will be added to enhance the EMI solution. See Picture below.



2. Since the LAN chipset does not support the Optimized Buffer Flush/Fill (OBFF) feature the components associated with the feature will be removed.
3. The VGA chip will be changed from IT6515 to IT6516A.
4. The Integration Guide will be updated to provide updated information.

**Customer Impact of Change and Recommended Action:**

These changes have been thoroughly evaluated to ensure there is no quality, reliability, or functional implication to our customers. Intel is not recommending additional qualification of these changes on platforms received from Intel.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

**Products Affected / Intel Ordering Codes:**

Product Code	MM#	Pre Change TA	Pre Change CA	Pre Change AA	Post Change TA	Post Change CA	Post Change AA
BOXNUC5CPYH	940289	H76561-100	H74562-403	H61145-402	H76561-101	H74562-404	H61145-403
BOXNUC5PPYH	943203	H74561-100	H76559-103	H76558-102	H74561-101	H76559-104	H76558-103

**PCN Revision History:**

**Date of Revision:**  
August 31, 2015

**Revision Number:**  
00

**Reason:**  
Originally Published PCN